

**Harmonized system of quality
assessment for electronic components**

Film and hybrid integrated circuits —

**Part 3: Self-audit checklist and report
for film and hybrid integrated circuit
manufacturers**

The European Standard EN 165000-3:1996 has the status of a
British Standard

ICS 31.200

Committees responsible for this British Standard

The preparation of this British Standard was entrusted by Technical Committee EPL/47, Semiconductors, to Subcommittee EPL/47/1, Film and hybrid integrated circuits, upon which the following bodies were represented:

- Federation of the Electronics Industry
- Ministry of Defence
- National Supervising Inspectorate (BSI Product Certification)

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National foreword

This British Standard has been prepared by Subcommittee EPL/47/1 and is the English language version of EN 165000-3:1996, *Film and hybrid integrated circuits Part 3: Self-audit checklist and report for film and hybrid integrated circuit manufacturers*, published by the European Committee for Electrotechnical Standardization (CENELEC).

Cross-references

Publication referred to	Corresponding British Standard
	BS EN 165000 <i>Film and hybrid integrated circuits</i>
EN 165000-1:1996	BS EN 165000-1:1996 <i>Generic specification. Capability approval procedure</i>
EN 165000-2:1996	BS EN 165000-2:1996 <i>Internal visual inspection and special tests</i>
EN 165000-4:1996	BS EN 165000-4:1996 <i>Customer information, product assessment level schedules and blank detail specification</i>

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Summary of pages

This document comprises a front cover, an inside front cover, pages i and ii, the EN title page, pages 2 to 98, an inside back cover and a back cover.

This standard has been updated (see copyright date) and may have had amendments incorporated. This will be indicated in the amendment table on the inside front cover.

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English version

Film and hybrid integrated circuits
Part 3: Self-audit checklist and report for film and hybrid
integrated circuit manufacturers

This European Standard was approved by CENELEC on 1996-03-05. CENELEC members are bound to comply with the CEN/CENELEC Internal Regulations which stipulate the conditions for giving this European Standard the status of a national standard without any alteration.

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This European Standard exists in three official versions (English, French, German). A version in any other language made by translation under the responsibility of a CENELEC member into its own language and notified to the Central Secretariat has the same status as the official versions.

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CENELEC

European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

Central Secretariat: rue de Stassart 35, B-1050 Brussels

Foreword

This European Standard was prepared by CLC/TC CECC SC 47AX (former CECC/WG 21), Film and hybrid integrated circuits.

The text of the draft was submitted to the Unique Acceptance Procedure and was approved by CENELEC as EN 165000-3 on 1996-03-05.

The following dates were fixed:

- latest date by which the (dop) 1997-03-01 EN has to be implemented at national level by publication of an identical national standard or by endorsement
- latest date by which the (dow) 1997-03-01 national standards conflicting with the EN have to be withdrawn

The present standard, EN 165000-3, *Film and hybrid integrated circuits — Part 3: Self-audit checklist and report for film and hybrid integrated circuit manufacturers*, is intended to be read in conjunction with the other parts of EN 165000, which are:

- *Part 1: Generic Specification — Capability approval procedure;*
- *Part 2: Internal visual inspection and special tests;*
- *Part 4: Customer information, product assessment level schedules and blank detail specification.*

This Part 3 is primarily intended as a pro-forma for the manufacturer and is not considered *essential* for a customer *in this form*.

Part 4 is considered an essential document for all users; in particular it includes a helpful introductory section which is aimed at potential customers and seeks to explain the underlying philosophy upon which the whole standard is based.

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1 Scope

This checklist is intended for the use of a hybrid microcircuit manufacturer's internal assessment team. It will provide the hybrid manufacturer and the ONS with ongoing information on process control demonstrating compliance with EN 165000-1. It is not intended to include Quality System requirements.

2 Document Information

2.1 Introduction

The checklist and subsequent report is for submission to the ONS in support of an application for approval to EN 165000-1 or as demonstration of continuing compliance at intervals not exceeding 1 year. Each section shall be completed or marked not applicable; sections which invoke mandatory process or inspection requirements are shown in ***bold italics***.

It should be noted that it is not the requirement or the intention that each section has to be answered with an affirmative, excepting mandatory requirements. The objective of the report is for the manufacturer to demonstrate that all manufacturing processes are under control by whatever means this is achieved.

Where supporting evidence is included, for example Engineering reports, SPC data etc, it should be appended to the report.

The manufacturer may use his own style of typeface to reproduce this document and produce his report. The ONS may subsequently validate any part of the submission as a process assessment.

2.2 Related documents.

EN 165000-1	Generic Specification for film and hybrid integrated circuits, capability approval procedure
EN 100114-1	Quality assessment procedures: Approval of manufacturers and other organisations.
CECC 00114/111	Quality assessment procedures. Capability approval of an electronic component manufacturing activity.
EN 100012	Basic specification: Radiographic inspection of electronic components.
EN 100015	Basic specification: Protection of electrostatic sensitive devices.
CECC 00016	Basic specification: Basic requirements for the use of statistical process control (SPC) in the CECC system.

3 General Requirements

The following pages contain:

- 3.1 Report front sheets and authentication.
- 3.2 Description of report/company structure
- 3.3 Approval information
- 3.4 Summary of testing
- 3.5 Analytical methods
- 3.6 Control of procurement sources and incoming material
- 3.7 Environmental control and static handling
- 3.8 Major change notification
- 3.9 Hybrid design

3.1 Self-audit checklist and report for thick and thin film hybrid integrated circuit manufacturers

Report No: Date:

Previous report No: Date:

Approval: Application/Periodic review/Extension/Major change*

Company name:

Address:

Postcode:

Telephone:

Telex:

Facsimile:

Company declaration.

The information contained herein is a true and accurate record of appraisals carried out between / / and / / .

Report compiled by: signed: date: / /

Report approved by: signed: date: / /

ONS Countersignature.

The information supplied in this report fully supports the Application/Periodic review/Extension/Major change* as detailed.

The following sections of this report have been subject to subsequent evaluation by the ONS:

For ONS: Signed: date: / /

*delete as appropriate.